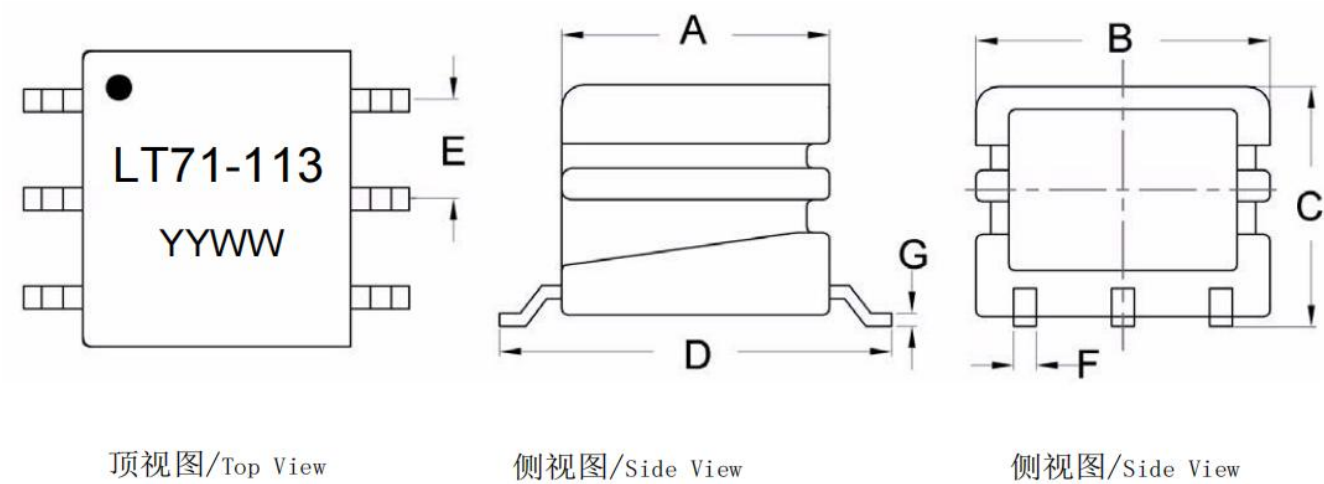
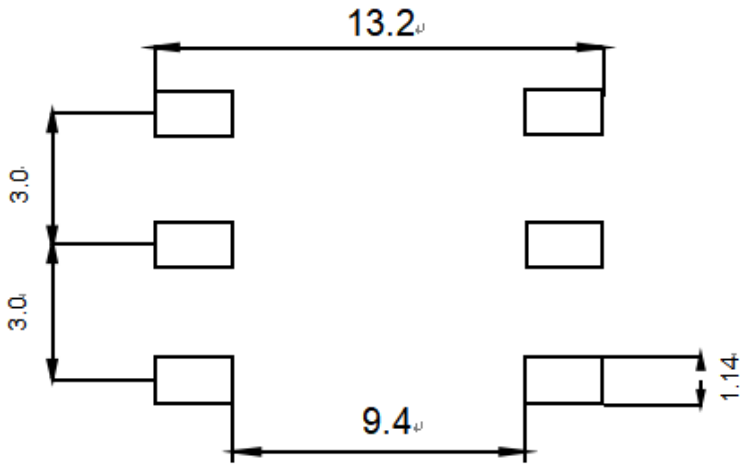


1. 机械轮廓 (MECHANICAL FIGURE & DIMENSIONS) UNIT:mm

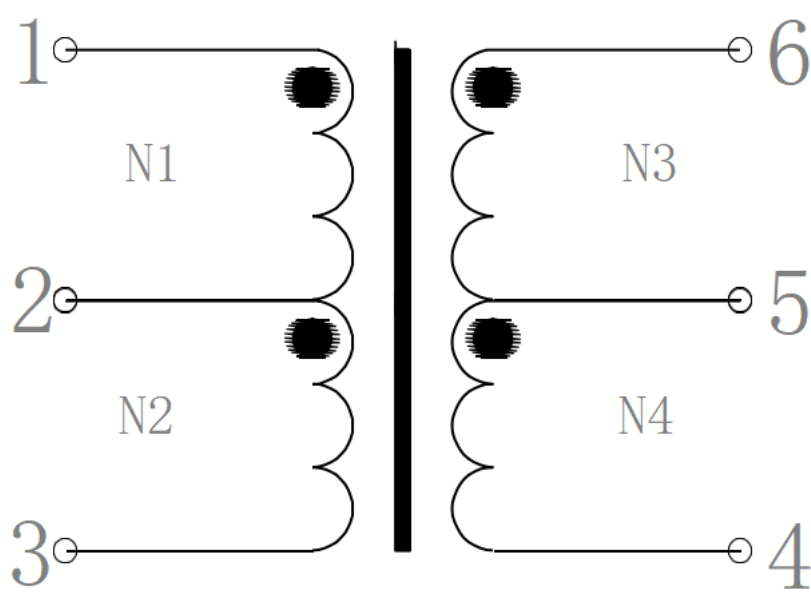


A	B	C	D	E	F	G
8.2±0.3	9.0±0.3	7.3±0.3	12.0±0.5	3.0±0.3	0.6	0.3



推荐焊盘/• Pad

2. 电气原理图 (WINDING CONNECTION)



3. 工艺要求 (TECHNICAL REQUIREMENT)

序号 NO.	端子/PIN		线材 Wire	圈数 Turns
	入/In	出/Out		
N1	1	2	TIW/H - $\Phi 0.12(\text{mm})$	9(ref)
N2	2	3	TIW/H - $\Phi 0.12(\text{mm})$	9(ref)
N3	6	5	FIW4 - $\Phi 0.12(\text{mm})$	12(ref)
N4	5	4	FIW4 - $\Phi 0.12(\text{mm})$	12(ref)

4. 订单信息 (ORDERING INFORMATION)

Part Number	Package Type	Package Size	Package Quantity	Mark Code
LTP71-113	SMD	9.00 mm * 8.20 mm	Tape and Reel, 350	LT71-113

5. 电气参数 (ELECTRICAL SPECIFICATION)

序号 NO.	项目 ITEMS	测量端 MEASURING POINT	规格参数 SPECIFICATION	测量条件(AT 25°C) TEST CONDITION
1	电感 Inductance	1-3	340uH Min.	100KHz/0.01V 串联测试
2	漏感 Leakage Inductance	1-3 (6-4 短接)	1.0uH Max.	100KHz/0.01V 串联测试
3	耦合电容 Coupling Capacitance	1-6	4.75pF Typ.	100KHz/0.01V 串联测试
4	伏秒积 Voltage-Time		10 Vus	N1/双极性波形
5	直流电阻 DC Resistacne	1-3	350mΩ Max.	(AT 20°C)
		6-4	330mΩ Max.	
6	匝比 Turns Ratio	(1-3):(6-4)	1:1.3	100KHz/0.01V
7	绝缘耐压 Insulation Voltage	(1-3) to (6-4)	5.0KV(AC)/60S/1mA	

6. AEC-Q200 资格认证概要 (AEC-Q200 QUALIFICATION SUMMARY)

Test Item	Test Standard	Test Conditions	Acceptance Criteria	Result
High Temperature Exposure Storage	MIL-STD-202 Method 108	125 ± 3°C, 1000 h	Inductance change ≤ ±10%; no mechanical damage	Pass*
Temperature Cycling	JESD22-A104C	-40 to +125°C, 1000 cycles; dwell time 30 min; transfer time ≤ 1 min	Inductance change ≤ ±10%; no mechanical damage	Pass*
Biased Humidity	MIL-STD-202 Method 103	85°C/85%RH, 1000 h; pre-conditioning 24 h at 40°C	Inductance change ≤ ±10%; no mechanical damage	Pass*
Mechanical Shock	MIL-STD-202 Method 213	Half-sine pulse, 100 g, 6 ms, 3 shocks per direction, 18 shocks total	Inductance change ≤ ±10%; no mechanical damage	Pass*
Vibration	MIL-STD-202 Method 204	10-2000 Hz, 5 g, X/Y/Z axes, 36 cycles total, 12 h	Inductance change ≤ ±10%; no mechanical damage	Pass*
ESD	AEC-Q200-002 Rev. B:2010 / ISO/DIS 10605	25 kV; contact discharge 6 kV; air discharge 12/16/25 kV	Inductance change within specified limit; no mechanical damage	Pass*
Solderability	J-STD-002E CN (2017-11)	Steam 93°C/8 h; bake 100°C/1 h; solder temperature 260°C	Solder coverage ≥ 95%	Pass*
Board Flex	AEC-Q200-005	Board deflection 2 mm; holding time 60 s	No mechanical damage	Pass*
Terminal Strength SMD	AEC-Q200-005	Applied force 17.7 N; holding time 60 s minimum	No mechanical damage	Pass*

7. 推荐回流焊曲线 (CLASSIFICATION REFLOW PROFILES)

Profiles are based on the IPC/JEDEC J-STD-020D standard*Figure 1 shows a typical profile and Table 1 lists the "reflow requirements" associated with this profile. Small volume SMD packages are typically classified at higher peak temperatures (**typical value is highlighted in bold, see Table 2**).Exceeding these conditions may lower product reliability.

Figure 1 – Reflow Profile for Solderability Testing

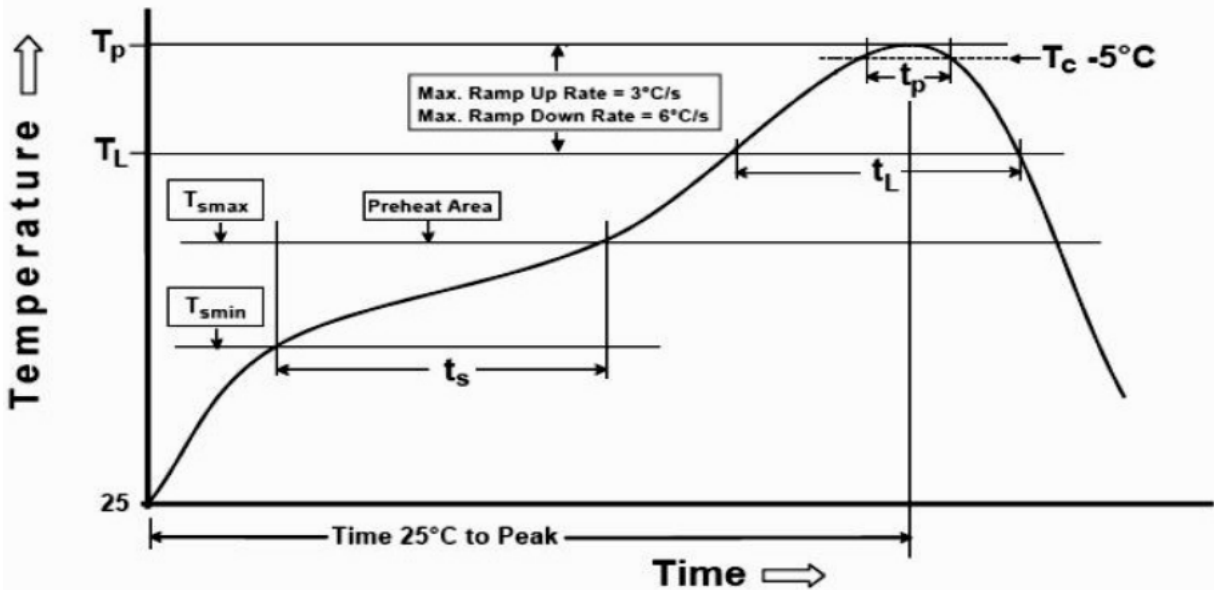


Table 1-Reflow Requirements for Solderability Testing

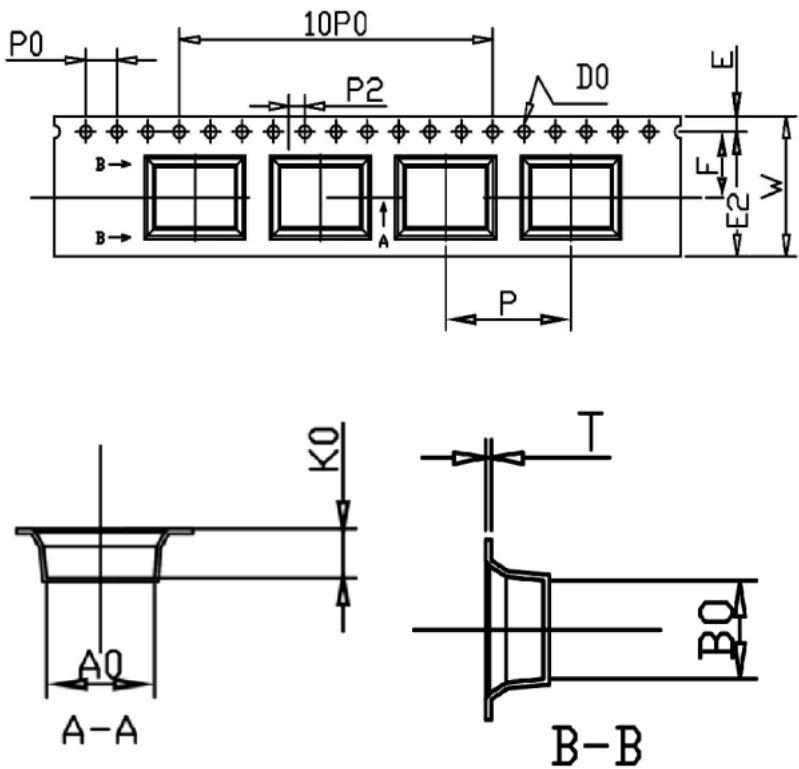
Reflow Parameter	Specification
Preheat temperature(T_{smin} - T_{smax})	150°C -200°C
Preheat Time(t_s)	60-180 seconds
Ramp-up Rate(T_L - T_p)	3°C/second maximum
Time Above 217°C(T_L)	60-150 seconds
Peak Temperature(T_p)	see Table 2
Time Within 5°C of Peak(T_p)	20-40 seconds
Ramp-down Rate(T_p - T_L)	6°C/second maximum
25°C to Peak Temperature(T to T_p)	8minutes maximum

*Table adapted from JEDEC Standard IPC/JEDEC J-STD-020D.

Table 2-Peak Temperatures for Lead Free Components

Package Thickness	Volume mm3	Volume mm3	Volume mm3
	<350	350-2000	>2000
<1.6mm	260+0-5°C	260+0-5°C	260+0-5°C
1.6-2.5mm	260+0-5°C	250+0-5°C	245+0-5°C
>2.5mm	250+0-5°C	245+0-5°C	245+0-5°C

Package Information



UNIT: mm	E	E2	F	P2	D0	P0	10P0	W	P	A0	B0	K0	T
Tolerance	±0.1	Min.	±0.1	±0.1	+0.1-0.0	±0.1	±0.2	±0.3	±0.1	±0.1	±0.1	±0.1	±0.05
Quantity	1.75	22.25	11.5	2.0	1.5	4.0	40.0	24.0	20.0	12.3	9.3	8.1	0.5

Important Notice

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